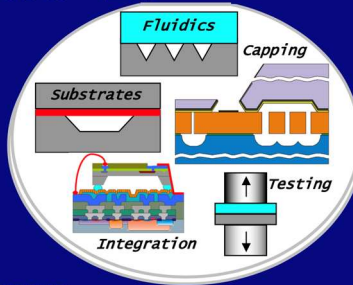


WaferBond'25

Conference on
Wafer Bonding
for Microsystems,
3D- and Wafer
Level Integration



Chemnitz / Germany

First announcement

WaferBond'25 will take place on the 3rd and 4th of December in Chemnitz, Germany and will include a pre-evening reception with Lab-Tours on 2nd of December at Fraunhofer ENAS. This conference on Wafer Bonding for Microsystems, 3D and Wafer Level Integration is organised by ErzM-Technologies UG, locally chaired by Fraunhofer ENAS and with the University of applied Science Schmalkalden as Technical Chair. All topics around wafer bonding, such as all types of wafer bonding processes and their process integration to enable new and advanced applications, fundamentals of new wafer bonding solutions, related metrology, characterisation techniques including reliability aspects as well as new developments of wafer bonding equipment will be covered by this networking event.

Don't miss the chance to join industry leaders, experts from top European research and technology organizations, and young scientists at the Conference on Wafer Bonding for Microsystems, 3D, and Wafer Level Integration, where the latest advancements in wafer bonding will be explored.

The objective of the conference is to provide a forum for open discussions across fundamental and applied sciences and industrial applications. It is dedicated to international bonding scientists, engineers, and attracts attendees from universities, research institutions and industries.

With more than 60 contributions as oral and poster presentations and over 100 participants expected we are looking forward to kindly welcome you to the European Capital of Culture 2025 in Chemnitz.

Location

This year's conference will be held in Chemnitz, Germany. Chemnitz is located close to Dresden and its international airport. Chemnitz combines history, modern art, culture, architecture, industry and modern science with University of Technology Chemnitz, two Fraunhofer Institutes. Chemnitz also holds the title of European Capital of Culture this year.

The conference will be held at hotel c/o56 in Chemnitz. There is a room contingent which can be used for booking; you will receive the password for this in the confirmation email when you register for the conference.

Local Chair by



Technical Chair by



Organized by



Key dates

Conference date	3 rd -4 th December 2025
Welcome Reception	2 nd December 2025
Conference Dinner	3 rd December 2025
Early-Bird Registration deadline:	1 st September 2025
Later posters until:	1 st September 2025

Conference fee

Early Bird
(until 30th September) 380 € + VAT

Regular 480 € + VAT

<https://www.waferbond.de/registration/>

Contact



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Planned Session Categories

- Fundamentals of Wafer Bonding
- Activation of Wafer Bonding Surfaces
- Silicon Science Award Ceremony
- Poster Pitch Session
- Glass Wafer Bonding
- Characterization and Metrology
- 3D-Integration by Wafer Bonding
- Technology Integration of Wafer Bonding Processes
- Die to Wafer Bonding Techniques

International Conference Committee

R. Knechtel	Schmalkalden University of Applied Sciences	M. Wiemer	Fraunhofer ENAS
F. Fournel	CEA Leti, Grenoble	V. Dubey	Fraunhofer ENAS
V. Larrey	CEA Leti, Grenoble	K. Turner	University of Pennsylvania
T. Suga	Meisel University Japan	A. Sanz-Velasco	Hightech Zentrum Aargau AG
F. Nicklaus	KTH Stockholm	A. Jourdain	IMEC, Belgium
J. Amthor	Robert Bosch GmbH	L. Peng	IMEC, Belgium
K. D. Hobart	Naval Research Lab.	N. Shigekawa	Osaka Metropolitan University
S. Wicht	X-FAB MEMS Foundry GmbH		

